

ightarrow ightarrow ightarrow Inductors (Coils) ightarrow Detailed Information

Inductors (Coils)

Product Top Pa	ge Search by Part	No. Search by Characteristics	Cross Reference	Catalog	Tech Notes	▼ more
MHQ04	02P3N8B	Т000				RoHS REACH SVHC-Free
Applications	Commercial C	Grade				PDF file of this page
Feature	Non-Mag Core Non-	Ion-Mag Core Non-Magnetic Core (Dielectric Ceramic)		, , , , , , , , , , , , , , , , , , ,		Contact
Series Type	MHQ-P	4HQ-P				Documents
Status	Production (Not Recommended for New Design) Recommended Alternate Part No. : <u>MHQ0402PSA3N8BT(</u> hangeability is not guaranteed.)		n) and	Images are for reference only and show exemplary products. rc		Catalog Catalog Control Certificate SVHC/REACH Certificate
Brand	TDK					Product Lineup Selection Guide] Inductors for high frequency conditions
Size						applications Update
Length(L)		0.44mm ±0.0	02mm			Technical Support Tools
Width(W)			0.24mm ±0.02mm			S-parameter
Thickness Hei	aht					SPICE Netlist (Simple)
•	-		0.24mm ±0.02mm			SPICE Netlist (Precision)
Recommended Land Pattern (A)			0.15mm to 0.20mm			Equivalent Circuit Model
Recommended Land Pattern (B) Recommended Land Pattern (C)			0.20mm Nom. 0.18mm to 0.20mm			
Recommended		0.101111100				
Electrical Cha	racteristics					
Inductance		3.8nH ±0.1n	3.8nH ±0.1nH at 500MHz			
Rated Current		200mA	200mA			
DC Resistance [Typ.]		250mΩ				
DC Resistance	[Max.]	500mΩ	500mΩ			
Self Resonant I	Frequency [Min.]	5GHz	5GHz			
Self Resonant Frequency [Typ.]		6.6GHz	6.6GHz			
Q [Min.]		10 at 500MF	10 at 500MHz			
Q [Тур.]		14 at 500M⊦	14 at 500MHz			
Other						
	o. Range (Including Se	lf-Temp. Rise) -55 to 125°C	,			
Soldering Method		Reflow	Reflow			
AEC-Q200	•					
Packing			aper)Taping [180mm	Reel]		
Package Quantity 20000pcs						
Weight 0.000		0.00011g	·			

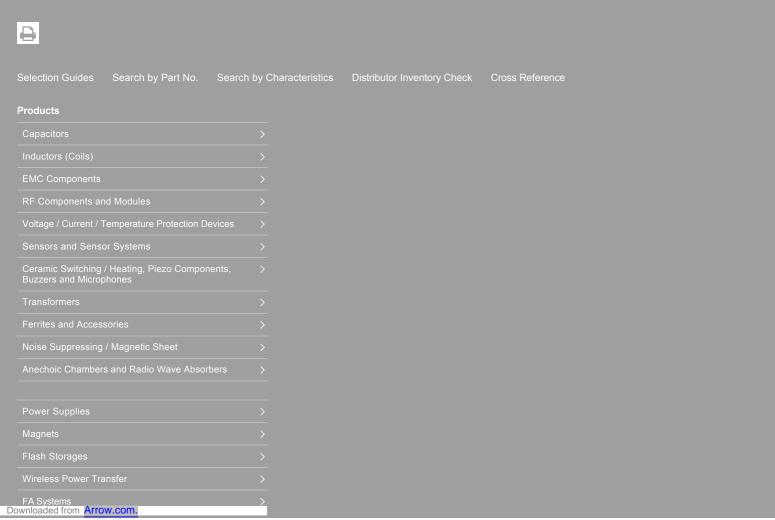
Rac

characteristics.)

Downloaded from Arrow.com.

Impedance

MHQ0402P3N8BT000	MHQ0402P3N8BT000
Change settings	Change settings
Inductance	Q
MHQ0402P3N8BT000	MHQ0402P3N8BT000
Change settings	Change settings



Transparent Conductive Film	>	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)		
Solar Cells		
Biosensor		
Application Specific IC (ASIC) Development and Supply		
Application Guides		
Technical Support		
Tech Library		
Environment		
Contact		
News		
Home		
About TDK		
TDK Worldwide		
Terms of Use Privacy Policy Cookie Policy		Copyright(c) 2019 TDK Corporation. All rights reserved. TDK logo is a trademark or registered trademark of TDK Corporation.